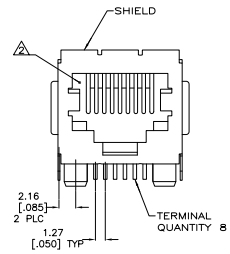
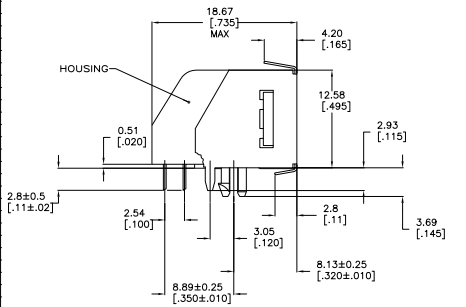
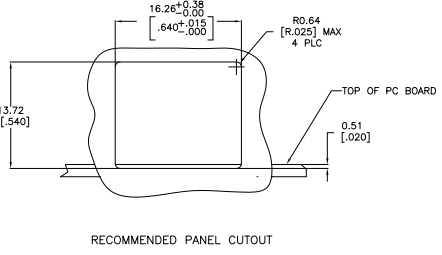
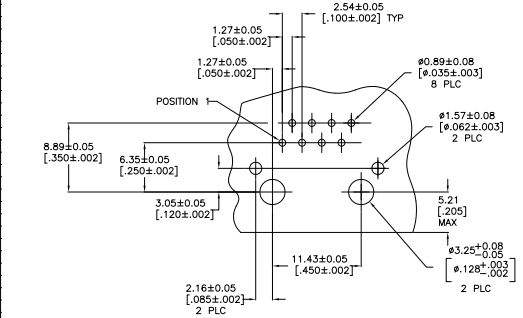
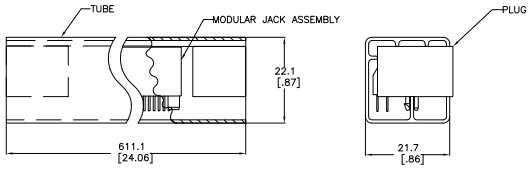
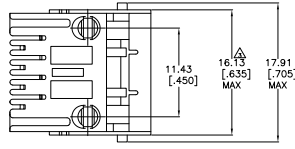


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REV	DATE	DESCRIPTION	BY	CHK	APP
AA	00				
B		ECO-07-00007			



- MATERIAL:  
 HOUSING - HTN NYLON MOLDING COMPOUND, 94 VO, COLOR: BLACK  
 TERMINAL - 0.36[0.14] THICK PHOS-BRONZE  
 PLATED WITH 1.27µm[0.00050] MINIMUM THICK HARD  
 GOLD IN LOCALIZED GOLD PLATE AREA AND  
 3.81µm[0.00150] MINIMUM THICK MATTE TIN IN  
 SOLDER AREA OVER 1.27µm[0.00050] THICK MINIMUM  
 NICKEL UNDERPLATE.  
 SHIELD - 0.25[0.010] THICK COPPER ALLOY PLATED  
 WITH 3.0µm[0.00120] MINIMUM REFLOWED TIN
- CAVITY CONFORMS TO FCC RULES AND  
 REGULATIONS, PART 68, SUBPART F
- DIMENSION MEASURED ALONG FRONT EDGES OF MATING FACE
- PACKAGED 31 ASSEMBLIES PER TUBE WITH BOTH ENDS PLUGGED  
 (SEE DETAIL A)



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)

RECOMMENDED PANEL CUTOUT

5569115-1  
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DESIGNED BY J. MAYER	DATE 08/05/05	DESIGNED BY J. MAYER	DATE 08/05/05	DESIGNED BY J. MAYER	DATE 08/05/05	DESIGNED BY J. MAYER	DATE 08/05/05	DESIGNED BY J. MAYER	DATE 08/05/05
APPROVED BY J. MAYER	DATE 08/05/05	APPROVED BY J. MAYER	DATE 08/05/05	APPROVED BY J. MAYER	DATE 08/05/05	APPROVED BY J. MAYER	DATE 08/05/05	APPROVED BY J. MAYER	DATE 08/05/05	APPROVED BY J. MAYER	DATE 08/05/05
CUSTOMER DRAWING		CUSTOMER DRAWING		CUSTOMER DRAWING		CUSTOMER DRAWING		CUSTOMER DRAWING		CUSTOMER DRAWING	